

APPLICATION DATA SHEET

Electronic Version v14

Stylesheet Version v14.0

Title of Invention	High Density Metal Capacitor Using Via Etch Stopping Layer as Field Dielectric in Dual-Damascene Interconnect Process
Application Type: regular, utility Attorney Docket Number: 1875.0230001/JDE	
Correspondence address: Customer Number: 26111 *26111*	
Continuing Data: This is a Continuation of US application number 09/753,664, filed 2001-01-04.	
Inventor Information: <u>Inventor 1:</u> Applicant Authority Type: Inventor Citizenship: CN Given Name: Liming Family Name: Tsau City of Residence: Irvine State of Residence: CA Country of Residence: US Address-1 of Mailing Address: 14591 Fir Avenue Address-2 of Mailing Address: City of Mailing Address: Irvine State of Mailing Address: CA Postal Code of Mailing Address: 92606 Country of Mailing Address: US Phone: Fax: E-mail:	

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